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MC21605L6W-SPTLY	2 x 16	5mm Character Height	LCD Module							
	Specification									
Version: 2		Date: 25/02/2016								
		Revision								
1	17/06/2015	First issue								
2	25/02/2016	Modify Precautions in use of LCD Modules & Static electricity tes								

Display F			
Character Count	2 x 16		
Appearance	Black on Yellow/Green		
Logic Voltage	5V		
Interface	Parallel		1
Font Set	English/Japanese		CHS
Display Mode	Transflective		ROHS ompliant
Character Height	5.55m <mark>m</mark>	C	ompliant
LC Type	STN		
Module Size	69.00 x 29.20 x 6.50mm		
Operating Temperature	-20°C ~ +70°C		
Construction	manuta COB	Box Quantity	Weight / Display
LED Backlight	White		

* - For full design functionality, please use this specification in conjunction with the ST7066U specification. (Provided Separately)

Display Accessories									
Part Number	Description								

Optional Variants									
Fonts	Appearances	Voltage							

General Specification

The Features is described as follow:

■ Module dimension: 69.0 x 29.2 x 6.5 (max.) mm

■ View area: 61.0 x 15.9 mm

■ Active area: 56.20 x 11.85 mm

■ Number of Characters: 16 characters x 2 Lines

■ Dot size: 0.55 x 0.65 mm

■ Dot pitch: 0.60 x 0.70 mm

■ Character size: 2.95 x 5.55 mm

■ Character pitch: 3.55 x 6.30 mm

■ LCD type: STN Positive, Yellow Green Transflective,

■ Duty: 1/16

■ View direction: 6 o'clock

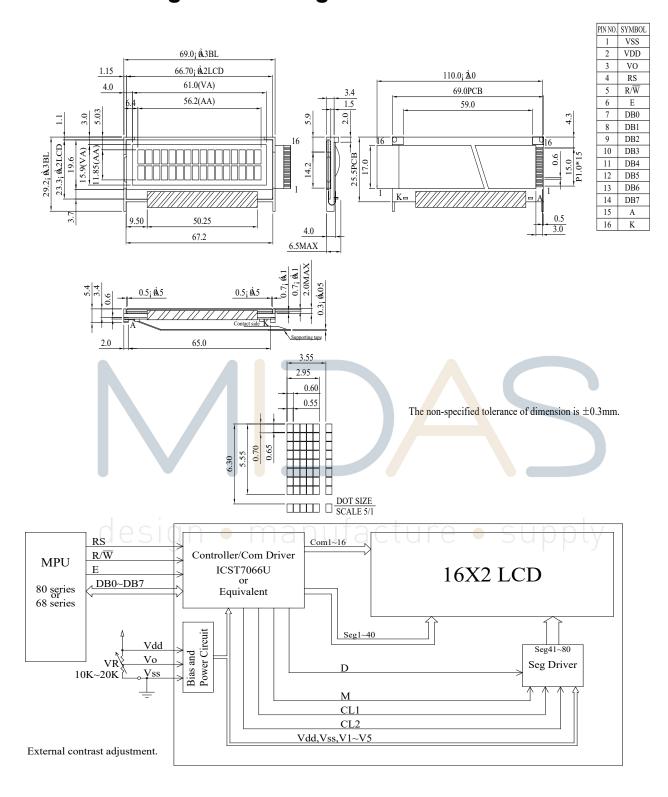
■ Backlight Type: LED, Yellow Green

■ IC: ST7066Usign • manufacture • supply

Interface Pin Function

Pin No.	Symbol	Level	Description
1	Vss	0V	Ground
2	V_{DD}	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read (Module> MPU) L: Write(MPU> Module)
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	SIHJLN	Data bus line UTacture Supply
14	DB7	H/L	Data bus line
15	Α	_	Power supply for B/L +
16	K	_	Power supply for B/L -

Contour Drawing & Block Diagram



Character located 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16

DDRAM address
DDRAM address
40 41 42 43 44 45 46 47 48 49 4A 4B 4C 4D 4E 4F

Character Generator ROM Pattern

Table.2

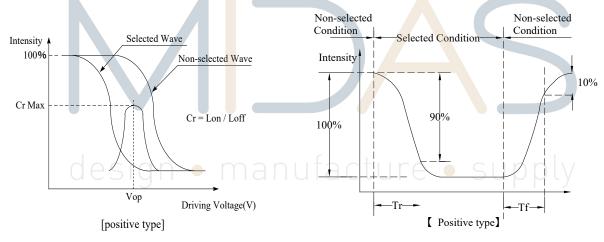
Upper 4 bit Lower 4 bit	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	LННН	HLLL	HLLH	HLHL	НЬНН	HHLL	HHLH	HHHL	нннн
LLLL	CG RAM (1)					====		: -					-===		=::=:	
LLLH	(2)		=					-::::			===				-===	
LLHL	(3)		11					====			====		!	.:-:		
LLHH	(4)				:	=	:					====			====-	::-:=
LHLL	(5)					*****		-i- i-					i			
LHLH	(6)	R	::. • • ::					ii			**					ļI
LHHL	(7)							ii							:::4	‡ ‡ •
LHHH	(8)		:=	17:				II						-	'	TI
HLLL	(1)	d	e s				na	nu	fa	ctı	J 1 6		- 6	J.D		,===
HLLH	(2)					!! !					====	-===	!		1	·!
HLHL	(3)			==	!									i		
НГНН	(4)			==	!-: <u>'</u>			-=-				-1-1-	i		:-:]==;
HHLL	(5)		==	-:				# # # # #			-1	::_:		!" <u>.</u> !	=:[:-	:::
HHLH	(6)						! • • • •								====	
нннг	(7)		==		ii	"	! <u>!</u>						::::	====	! !	
нннн	(8)						====				: : :		:		11	

Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	20	ψ= 180°
View Areale	θ	CR≧2	0	_	40	ψ= 0°
View Angle	θ	CR≧2	0	_	30	ψ= 90°
	θ	CR≧2	0	_	30	ψ= 270°
Contrast Ratio	CR	_	_	3	_	_
	T rise	_	_	150	200	ms
Response Time	T fall	_	_	150	200	ms

Definition of Operation Voltage (Vop)

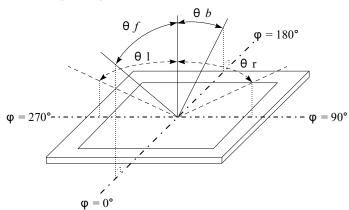
Definition of Response Time (Tr, Tf)



Conditions:

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≧2)



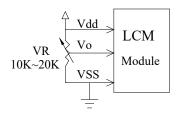
Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	T _{ST}	-30	_	+80	°C
Input Voltage	Vı	Vss	_	V_{DD}	V
Supply Voltage For Logic	V _{DD} -V _{SS}	-0.3	_	7	V
Supply Voltage For LCD	V _{DD} -V _o	-0.3	_	13	V

Electrical Characteristics

Item	Symb <mark>ol</mark>	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V _{DD} -V _{SS}	-	4.5	5.0	5.5	>
Supply Voltage For LCD		Ta=-20°C			_	V
*Note desig	V _{DD} -V ₀	Ta=25°C	t 4.1	4.2	4.3	oly
		Ta=70°C	_			V
Input High Volt.	ViH	_	0.7 V _{DD}	1	V _{DD}	V
Input Low Volt.	VıL	_	Vss	1	0.6	V
Output High Volt.	Vон	_	3.9	_	VDD	V
Output Low Volt.	Vol	_	0	_	0.4	V
Supply Current	I _{DD}	V _{DD} =5.0V	0.1	0.13	0.15	mA

^{*} Note: Please design the VOP adjustment circuit on customer's main board



Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	МАХ	UNIT	TEST CONDITION		
Supply Current	ILED	89.6	112	168	mA	V=2.2V		
Supply Voltage	V	_	2.2	_	v	_		
Reverse Voltage	VR	_	_	5	v	_		
Luminous	IV	52.8	60		CD/M ²	ILED=112mA		
Intensity	IV	52.0	60		CD/IVI	ILED-112IIIA		
LED Life Time	_		50000		Hr.	ILED≦112mA		
Color Yellow Green								

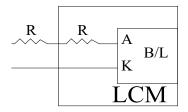
Note: The LED of B/L is drive by current only, drive voltage is for reference only.

drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.

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2.Drive from pin15,pin16



ill never get Vee output from pin15)

Reliability

Content of Reliability Test (Wide temperature, -20°c~70°C)

Environmental Test									
Test Item	Content of Test	Test Condition	Note						
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2						
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2						
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs							
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1						
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2						
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles							
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3						
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times							

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Inspection specification

NO	Item			Criterion		AQL		
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 						
	Black or white	1.8 Contrast def	ect. lack spots	on display ≦0.25i	mm, no more than			
02	spots on LCD (display only)	2.2 Densely spa 3mm	iced: No n	nore than two spots	s or lines within	2.5		
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi = (x + y) / $ 3.2 Line type : (A	² ↓ TY	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Acceptable Q TY Accept no dense 2 As round type	2.5		
04	Polarizer bubbles	If bubbles are vi judge using blac specifications, n to find, must che specify direction	ck spot ot easy eck in	Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ $Total Q TY$	Acceptable Q TY Accept no dense 3 2 0 3	2.5		

NO	Item	Criterion A				
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination				
		Symbols Define: x: Chip length y: Chip length k: Seal width t: Chip length: 6.1 General glass chip : 6.1.1 Chip on panel surf 2: Chip thickness Z≤1/2t 1/2t < z≤2t Olf there are 2 or more 6.1.2 Corner crack:	spots, white spots, con Chip width z: Chip Glass thickness a: LCI face and crack between y: Chip width Not over viewing area Not exceed 1/3k chips, x is total length	thickness D side length x: Chip length x≤ 1/8a x≤ 1/8a of each chip.	AQL 2.5	
		z: Chip thickness	y: Chip width	x: Chip length		
		Z≦1/2t	Not over viewing area	x≦1/8a		
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a		
		⊙ If there are 2 or more chips, x is the total length of each chip.				

x: k: L:	: Electrode pad length	idth z: Chip tl hickness a: LCD				
k:	: Seal width t: Glass the control of	•				
L:	: Electrode pad length	nickness a: LCD				
			side length			
6.	2 Protrusion over terminal:	L: Electrode pad length				
	6.2 Protrusion over terminal :					
6.	6.2.1 Chip on electrode pad :					
	Z					
	y: Chip width x:	Chip length	z: Chip thickness			
	y≦0.5mm	x≦1/8a	$0 < z \leq t$			
6.	6.2.2 Non-conductive portion:					
06 Glass crack	y X		1 Z	2.5		
o e	y: Chip width	x: Chip length	z: Chip thickness			
	y≦ L	x≦1/8a	$0 < z \le t$			
	⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO					
	• •		g to electrode terminal			
	specifications.					
	\odot If the product will be h	eat sealed by the	customer, the alignment			
	mark not be damaged.					
6.	6.2.3 Substrate protuberance and internal crack.					
	X	y: width	x: length			
		y≦1/3L	x ≦ a			
	y					

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	2.5 2.5 0.65 2.5 0.65 2.5 2.5
		X * Y<=2mm2	
11	Soldering	11.1 No un-melted solder paste may be present on the PCB.11.2 No cold solder joints, missing solder connections, oxidation or icicle.11.3 No residue or solder balls on PCB.	2.5 2.5 2.5
		11.4 No short circuits in components on PCB.	0.65

NO	Item	Criterion		
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.		
		12.2 No cracks on interface pin (OLB) of TCP.12.3 No contamination, solder residue or solder balls on product.	0.65	
			2.5	
		12.4 The IC on the TCP may not be damaged, circuits.	2.5	
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to	2.5	
		sever.	2.5	
12	General	12.6 The residual rosin or tin oil of soldering (component or chip		
	appearance	component) is not burned into brown or black color.		
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65	
		12.8 Pin type must match type in specification sheet.	0.65	
		12.9 LCD pin loose or missing pins.	0.65	
		12.10 Product packaging must the same as specified on	0.00	
		packa <mark>gi</mark> ng specification sheet.	0.65	
		12.11 Prod <mark>uc</mark> t dimension and structu <mark>re</mark> must conform to product		
		specifi <mark>ca</mark> tion sheet.		
		12.12 Visu <mark>al</mark> defect outside of VA is not conside <mark>re</mark> d to be		
		rejection.		

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Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) MIDAS have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) MIDAS have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, MIDAS have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

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Material List of Components for RoHs

1. MIDAS hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement : (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.